

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1.       **[Original]** A titanium-copper alloy having high strength and conductivity as a copper alloy comprising:

three to four percent by mass of Ti,  
residual Cu, and  
inevitable impurities,

wherein the area percentage (S(%)) of a Cu-Ti intermetallic compound phase observed in a section perpendicular to the rolling direction is represented by the following formula:

$$S(\%) \geq 8.1 \times [\text{Ti}] - 17.7$$

where [Ti] represents the Ti content in percent by mass.

Claim 2.       **[Original]** A titanium-copper alloy according to Claim 1, wherein a conductivity is 16% IACS or more, and 0.2% proof stress is 800 MPa or more.

Claim 3.       **[Withdrawn]** A method of producing a titanium-copper alloy according to Claim 1 or 2 comprising the steps of:

hot-rolling, cold-rolling, solution-treating, cold-rolling, and aging an ingot,

wherein a cold working degree prior to the aging is 15% or more, the aging temperature is from 350°C to 450°C, the aging time is from 5 to 20 hours, and the average cooling rate from the aging temperature after the aging to 300°C is 50°C/h or less.